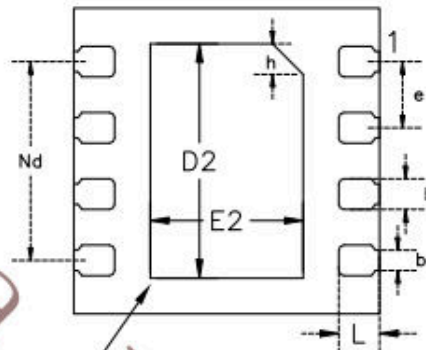
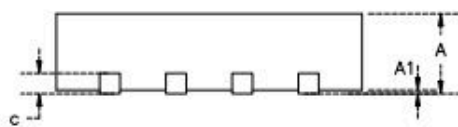


TOP VIEW



EXPOSED THERMAL PAD ZONE BOTTOM VIEW



SIDE VIEW

SYMBOL	MIN	NOM	MAX
A	0.7	0.75	0.8
A1	-	0.02	0.05
b	0.25	0.3	0.35
b1	0.2REF		
c	0.18	0.2	0.22
D	2.9	3.0	3.1
D2	2.2	2.3	2.4
e	0.65BSC		
Nd	1.95BSC		
E	2.9	3.0	3.1
E2	1.4	1.5	1.6
L	0.35	0.4	0.45
h	0.25	0.3	0.35

NOTES:
 1. ALL DIMENSIONS REFER TO JEDEC STANDARD MO-229 (VCCD-3)
 2. DIMENSION D DOES NOT INCLUDE MOLD FLASH
 3. DIMENSION E1 DOES NOT INCLUDE MOLD FLASH
 4. FLASH OR PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE.



上海季丰电子科技有限公司
 GIGA FORCE ELECTRONICS CO., Limited

制图	王磊	Title	DFN8L (3X3X0.75)-P0.65	
核准	何桂港	POD No	POD-SHJF-05	
日期	2022.3.6	DIMENSIONS IN:	mm	Rev:A